sub C1 B2

2. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein each of said metallic films is a single layer made of a metallic substance.

sub C2 B3

5. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein:

said connecting parts respectively comprise bonding wires, and bonding balls respectively provided to the metallic films; and

said bonding wires are bonded to said electrode pads and said bonding balls.

sub C3 B4

7. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films,

wherein said resin package includes a first resin portion on which the chip is provided, and a second resin portion which covers the chip.

15. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package, said resin projections extending downwards from the mount-side surface and laterally extending from at least one side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films,

wherein each of said metallic films is a single layer made of a metallic substance.

18. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package, said resin projections extending downwards from the mount-side surface and laterally extending from at least one side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein:

said connecting parts respectively comprise bonding wires, and bonding balls respectively provided to the metallic films; and

said bonding wires are bonded to said electrode pads and said bonding balls.

20. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package, said resin projections extending downwards from the mount-side surface and laterally extending from at least one side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein said resin projections laterally extend from a plurality of side surfaces of said resin package.

21. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package, said resin projections extending downwards from the

mount-side surface and laterally extending from at least one side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films,

wherein said resin projections laterally extend from only one side surface of said resin package.

44. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films,

wherein:

said connecting members respectively comprise bumps provided between the electrode pads of the chip and the metallic films.

45. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein:

said metallic films respectively have lead portions, which are sealed by the resin package and extend toward the chip; and

B8 said connecting parts include bumps provided between the electrode pads of the chip and the lead portions of the metallic films.

cont.

46. (Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a mount-side surface of the resin package;

metallic films respectively provided to the resin projections; and

connecting parts electrically connecting electrode pads of said chip and the metallic films, wherein:

said metallic films respectively have lead portions, which are sealed by the resin package and extend toward the chip, said lead portions having recess portions; and

said connecting parts include bumps, which are positioned in said recess portions and are provided between the electrodes pads of the chip and the lead portions of the metallic films.